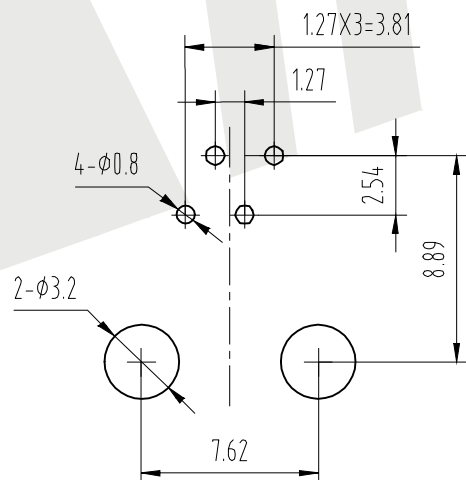
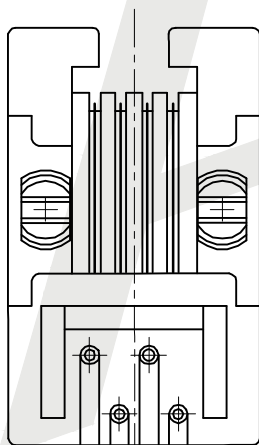
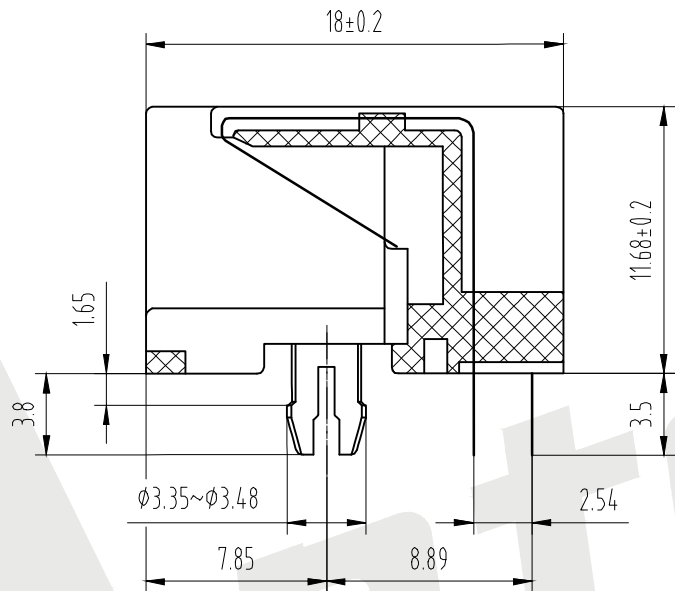
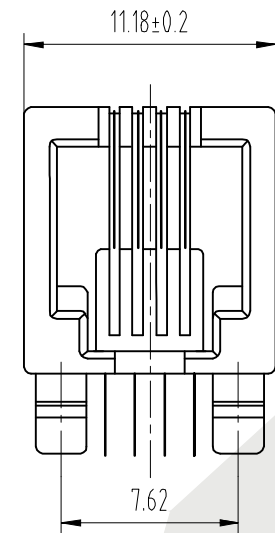


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING $1\mu \sim 50\mu$ "OVER NICKEL IN CONTACT AREA. 150μ " TIN PLATIN. OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mm THICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVIORNMENTAL

- 1. STORAGE : -40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

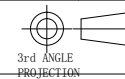
Order code:

ATRJ5321 — 4P — 4C — X — A — A
 ① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
 G0:Gold flash
 G1: 3U" Gold
 G2: 5U" Gold
 G3:10U" Gold
 G4:15U" Gold
 G5:30U" Gold
 SN: Tin
- ⑤ Shield
 A:W/O Shield
 B:Half Shield
 C:Shield W/Eml
 D:Shield W/O Eml
- ⑥ Ports
 A:1X1P
 B:1X2P
 C:1X4P
 D:1X5P
 E:1X6P
 F:1X8P

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
 DRAW Wu Sai DATE 22/03/2018
 CHECK BobYang DATE 22/03/2018



Antenk® ANTENK ELECTRONICS CO.,LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE: RJ11 Jack 4P4C, Side entry, 1X1Port, Full plastic

DRAWING NO: ATRJ5321-4P4C-X-A-A

PRODUCT NO: ATRJ5321-4P4C-X-A-A

REV	DESCRIPTION	DATE
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